

Kulicke & Soffa Industries, Inc.

Kulicke & Soffa Introduces New Offerings at SMT Hybrid Packaging Show Press Conference on May 6, 2015 at 10:00 a.m. CEST

SINGAPORE--(BUSINESS WIRE)-- Kulicke and Soffa Industries, Inc. (NASDAQ: KLIC) ("Kulicke & Soffa", "K&S" or the "Company") will be showcasing newly launched products and state-of-the art equipment during the SMT Hybrid Packaging show in Germany from May 5-7.

The new, enhanced capability, hybrid wedge bonder, the Asterion™, was successfully launched in March in China and will be debuting in Europe at the SMT show. The new Configurable High-Power Bond Head will also be introduced at the show along with the iFlex T2, iFlex H1, and Hybrid 3 advanced pick-and-place solutions and the PowerFusion™ High Performance Semiconductor wedge bond solution.

The Asterion Wedge bonder is built on an enhanced architecture that includes an expanded bond area, new robust pattern recognition capabilities and extremely tight process controls. Together these deliver heightened productivity, bonding quality, and reliability. The enlarged bondable area enhances flexibility and reduces line integration costs.

The New Configurable High Power Bond Head addresses the industry's growing and changing applications needs by handling a multitude of interconnect materials including large and small aluminum wire, copper wire, PowerRibbon™, as well as aluminum copper-clad ribbon.

PowerFusion - High Performance Semiconductor Wedge Bonder is driven by a new powerful direct-drive motion system and expanded pattern recognition capabilities which deliver industry-leading productivity and reliability. The iFlex T2 and H1 systems offer best in class flexibility, fast changeover and the lowest defect per million (DPM) rates in the industry. These advanced solutions can place all types of passive and discrete SMT components and also handle multifunctional and end-of-line placements.

The Hybrid 3 is a multi-application solution for advanced packaging with one of the lowest DPM and highest throughput in the industry. It delivers a placement accuracy of less than 10 µm, making it ideal for wafer level packaging, FOWLP, SiP, MCM, flip-chip, modules and embedded components. Having evolved from the high speed AX/iX product family, the Hybrid 3 is highly capable of placing both die and passive component with a single machine.

Customers can see these technical solutions at the SMT Hybrid Packaging show at the Messezentrum in Nuremberg, Germany, Hall 7A, Booth #317, from May 5-7, 2015. There will be a press conference at 10:00 a.m. CEST on May 6, 2015 in the booth to introduce the new wedge bonding solutions.

About Kulicke & Soffa

Kulicke & Soffa (NASDAQ: KLIC) is a global leader in the design and manufacture of semiconductor, LED and electronic assembly equipment. As a pioneer in this industry, K&S has provided customers with market leading packaging solutions for decades. In recent years, K&S has expanded its product offerings through strategic acquisitions and organic development, adding advanced packaging, advanced SMT, wedge bonding and a broader range of expendable tools to its core ball bonding products. Combined with its extensive expertise in process technology, K&S is well positioned to help customers meet the challenges of assembling the next-generation semiconductor and LED devices. (www.kns.com)

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